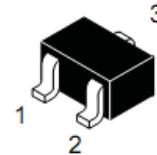


### Single P-Channel, -20V, -3.2A, Power MOSFET

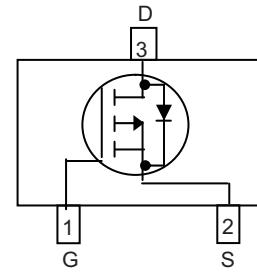
<b>V<sub>DS</sub> (V)</b>	<b>R<sub>ds(on)</sub> (Ω)</b>
<b>-20</b>	0.056@ V <sub>GS</sub> = - 4.5V
	0.069@ V <sub>GS</sub> = - 2.5V
	0.086@ V <sub>GS</sub> = - 1.8V



**SOT-23**

### Descriptions

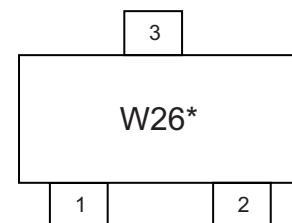
The WPM2026 is P-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WPM2026 is Pb-free and Halogen-free.



**Pin configuration (Top view)**

### Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-23



W26= Device Code

\* = Month (A~Z)

### Marking

### Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

### Order information

<b>Device</b>	<b>Package</b>	<b>Shipping</b>
WPM2026-3/TR	SOT-23	3000/Reel&Tape

**Absolute Maximum ratings**

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	±12	V
Gate-Source Voltage	V <sub>GS</sub>	±12		
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-3.2	A
	T <sub>A</sub> =70°C		-2.6	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.9	W
	T <sub>A</sub> =70°C		0.6	
Continuous Drain Current <sup>b</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-2.9	A
	T <sub>A</sub> =70°C		-2.3	
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	0.7	W
	T <sub>A</sub> =70°C		0.5	
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>	-12		A
Operating Junction Temperature	T <sub>J</sub>	150		°C
Lead Temperature	T <sub>L</sub>	260		°C
Storage Temperature Range	T <sub>stg</sub>	-55 to 150		°C

**Thermal resistance ratings**

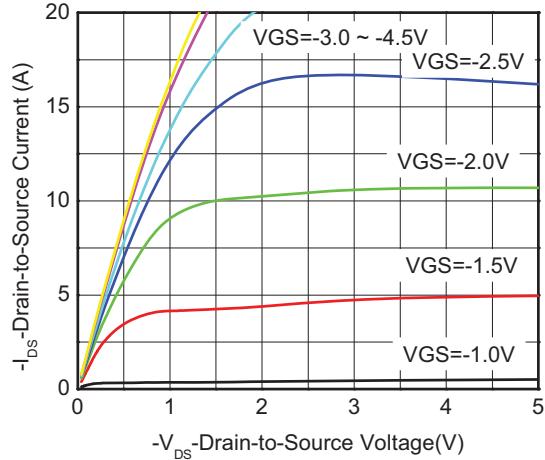
Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	105	130
	Steady State		120	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t ≤ 10 s	R <sub>θJA</sub>	130	160
	Steady State		145	
Junction-to-Case Thermal Resistance	R <sub>θJC</sub>	40	60	

- a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper  
 b Surface mounted on FR4 board using minimum pad size, 1oz copper  
 c Repetitive rating, pulse width limited by junction temperature, t<sub>p</sub>=10μs, Duty Cycle=1%  
 d Repetitive rating, pulse width limited by junction temperature T<sub>J</sub>=150°C.

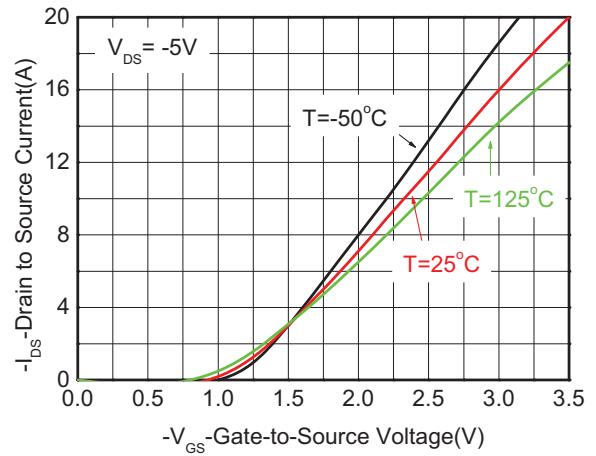
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = -250μA	-20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -16 V, V <sub>GS</sub> = 0V			-1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±12V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = -250μA	-0.35	-0.6	-1.0	V
Drain-to-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3.2A		56	65	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2.8A		69	81	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -2.3A		86	110	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -5 V, I <sub>D</sub> = -3.6A		10		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = -10 V		1130		pF
Output Capacitance	C <sub>OSS</sub>			120		
Reverse Transfer Capacitance	C <sub>RSS</sub>			115		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = -4.5 V, V <sub>DS</sub> = -10 V, I <sub>D</sub> = -2.7A		11		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.6		
Gate-to-Source Charge	Q <sub>GS</sub>			1.3		
Gate-to-Drain Charge	Q <sub>GD</sub>			2.7		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = -4.5 V, V <sub>DD</sub> = -10 V, R <sub>L</sub> =3.5 Ω, R <sub>G</sub> =6 Ω		16		ns
Rise Time	tr			20		
Turn-Off Delay Time	td(OFF)			65		
Fall Time	tf			15		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -1.0A		-0.62	-1.5	V

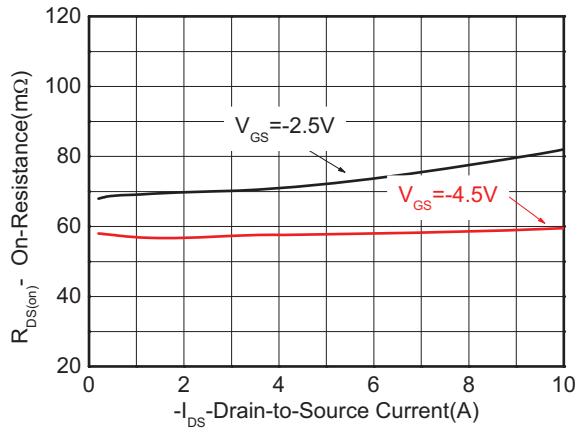
**Typical Characteristics (Ta=25°C, unless otherwise noted)**



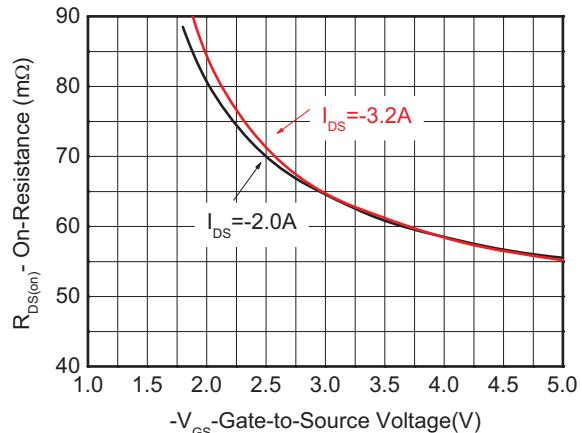
**Output characteristics**



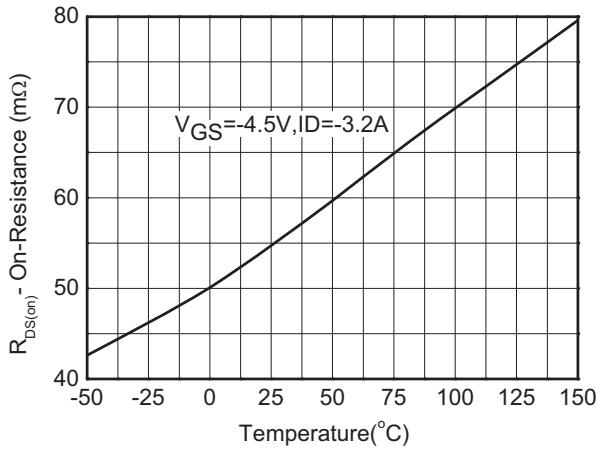
**Transfer characteristics**



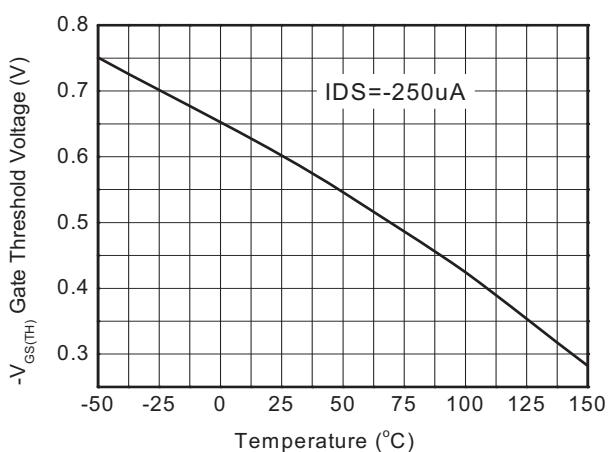
**On-Resistance vs. Drain current**



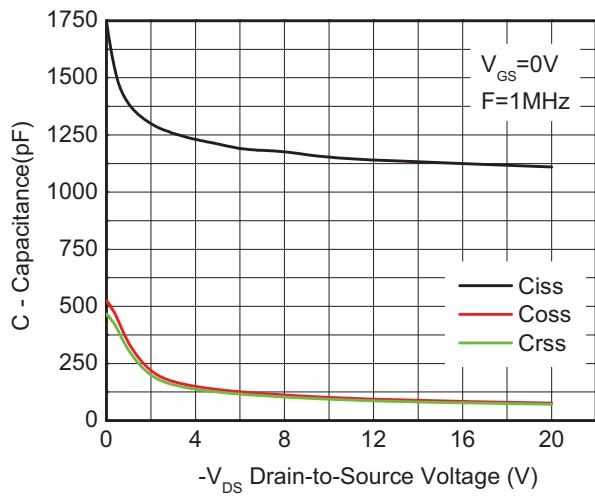
**On-Resistance vs. Gate-to-Source voltage**



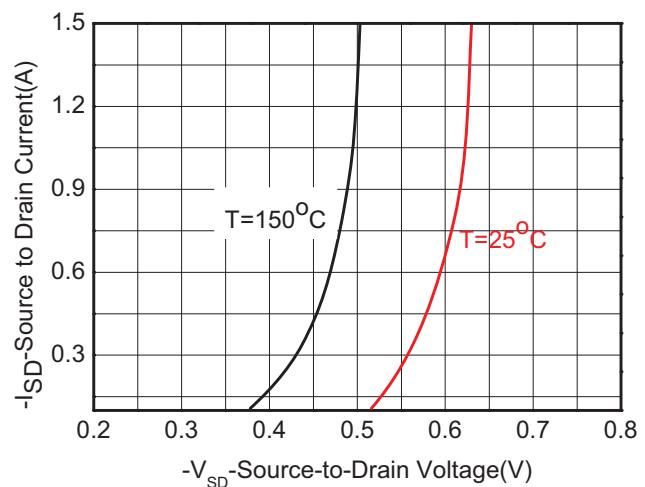
**On-Resistance vs. Junction temperature**



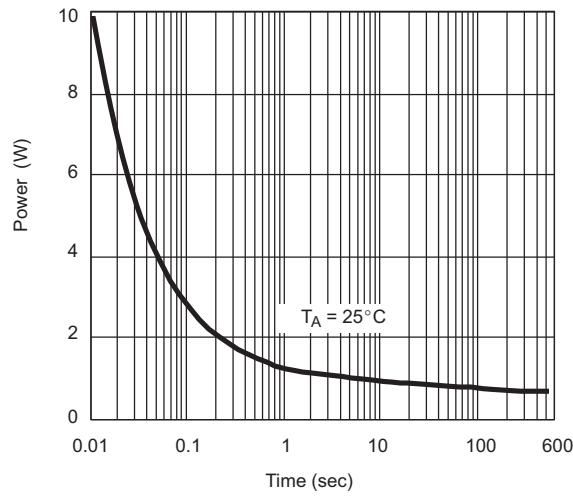
**Threshold voltage vs. Temperature**



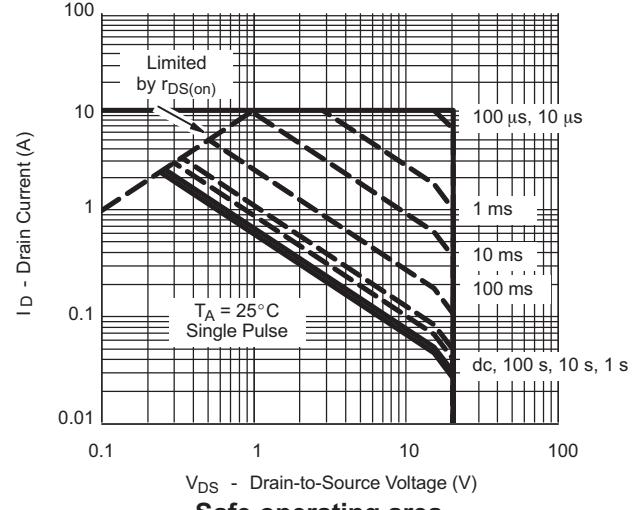
**Capacitance**



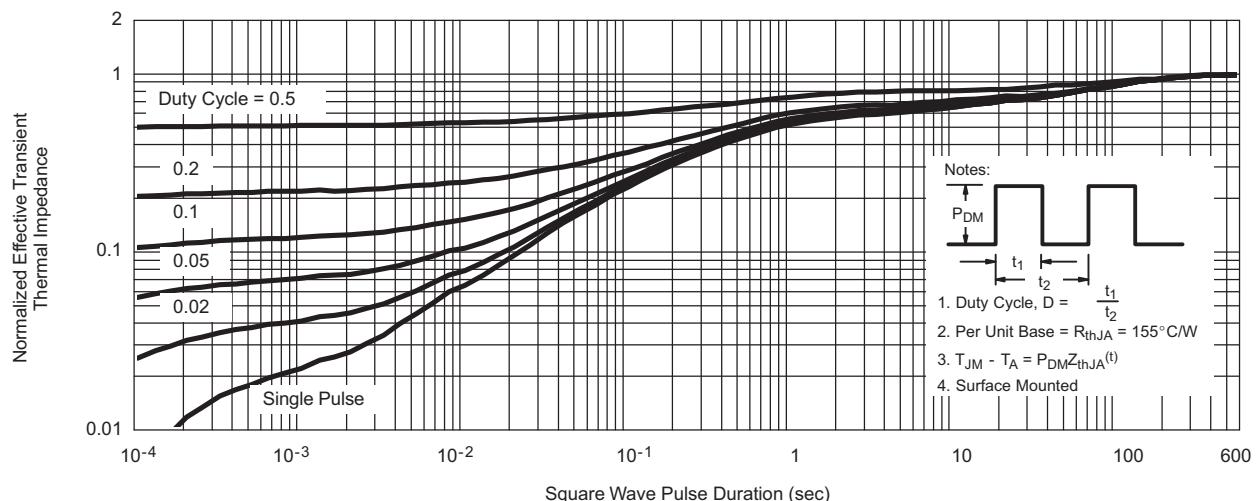
**Body diode forward voltage**



**Single pulse power**



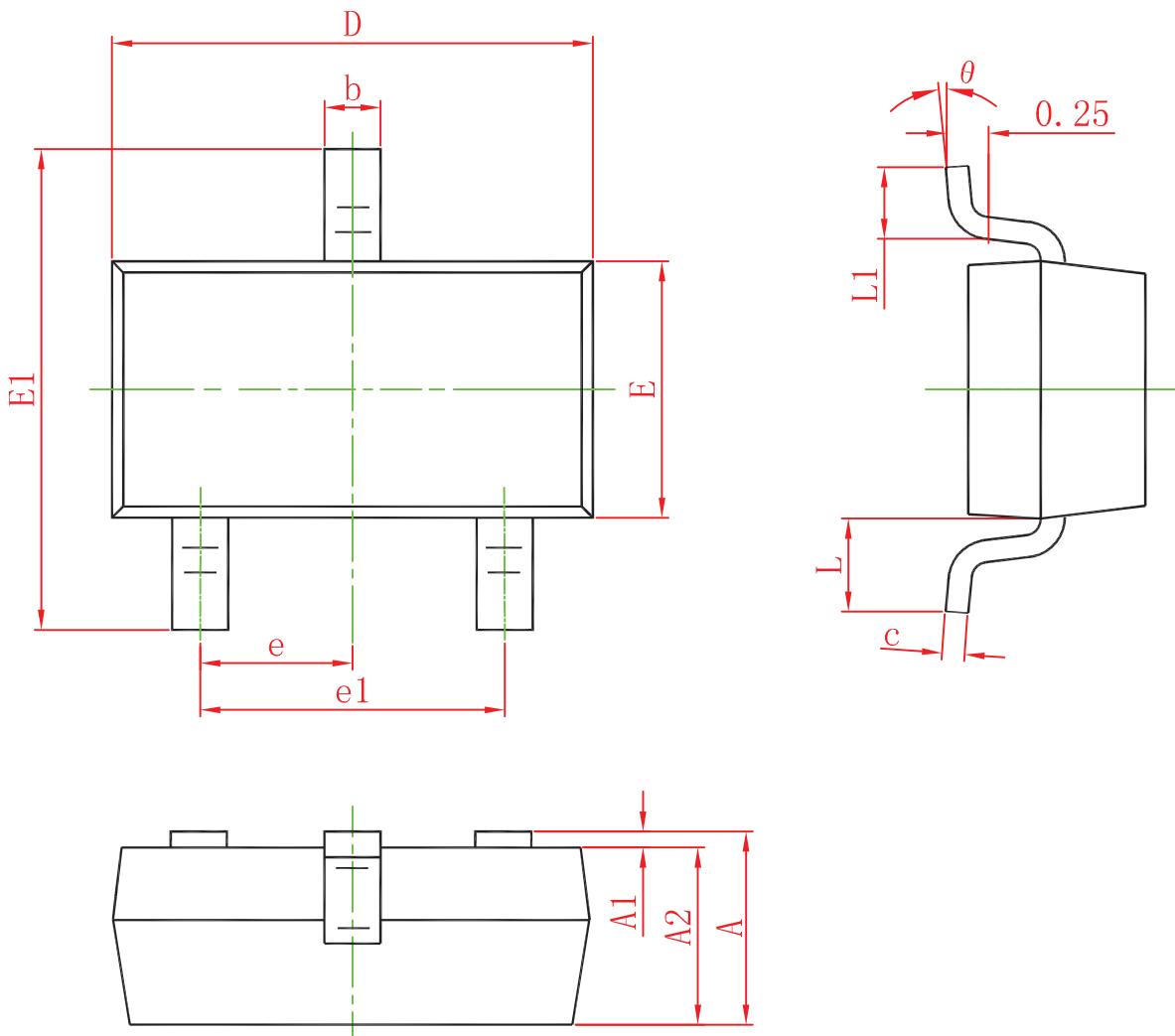
**Safe operating area**



**Transient thermal response (Junction-to-Ambient)**

## Package outline dimensions

SOT-23



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
A2	0.900	0.975	1.050
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
E1	2.250	2.400	2.550
e	0.950TYP		
e1	1.800	1.900	2.000
L	0.550REF		
L1	0.300		0.500
θ	0°		8°